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瑞萨电子公司网址：http://www.renesas.com

2010年4月1日
瑞萨电子公司

【发行】瑞萨电子公司（http://www.renesas.com）

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二极管

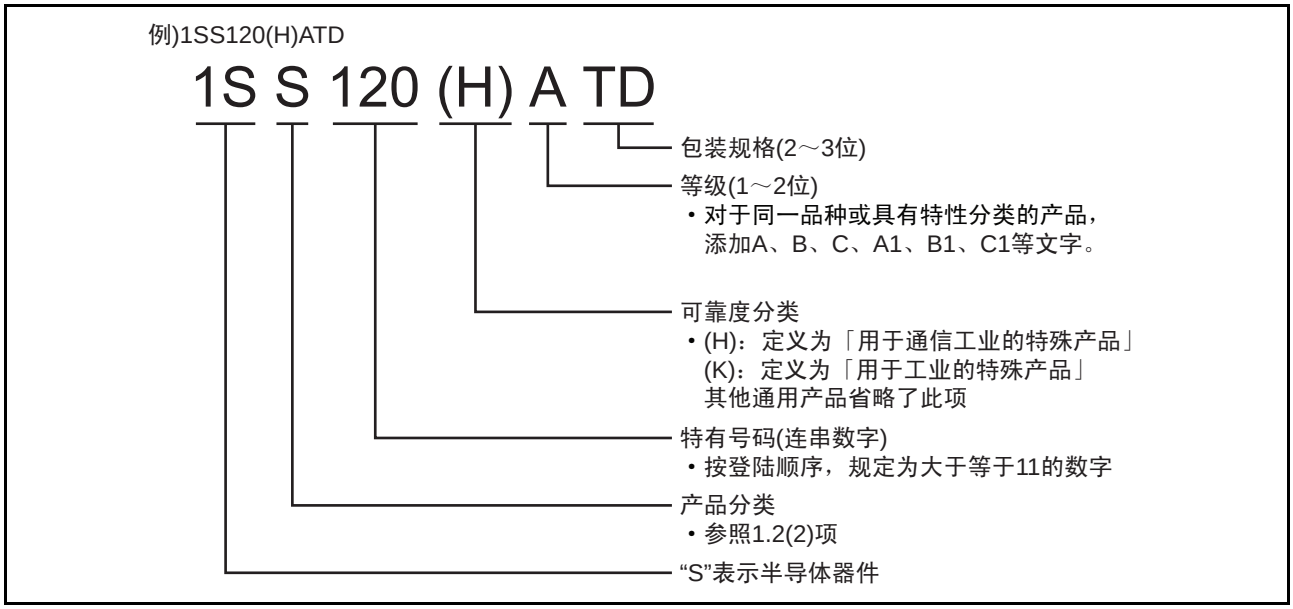
瑞萨二极管的命名方法

1. 二极管的命名方法

1.1 型号设定的基本原则

(1) Si Diode 的命名是基于电子信息技术产业协会标准 (EIAJ-ED-4001) 的规定，在登录 （社）电子信息技术产业协会 (JEITA) 后，由 JEITA 命名的。

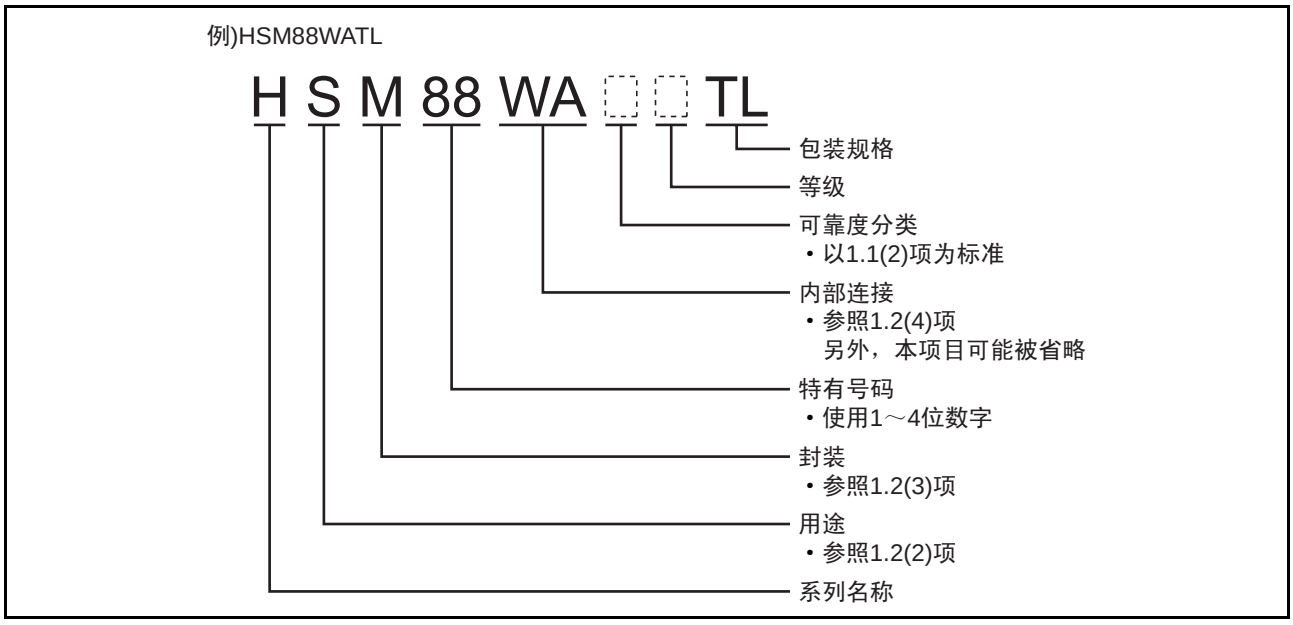
(2) 基本结构



1.2 二极管型号命名的例外事项 （原日立二极管独有型号）

在1.1 型号设定的基本原则中，产生问题的情况下，可通过下列结构获得原日立二极管特有的型号。

(1) 基本结构



(2) 表示用途的英文字母标注方法
参照下表，用1个英文字母表示用途 （产品分类）。

表示用途的英文字母	用途 （产品分类）
S	信号二极管
V	变容二极管 PIN二极管

表示用途的英文字母	用途 （产品分类）
R	高速开关二极管
Z	齐纳二极管

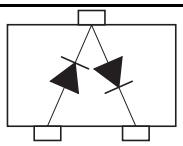
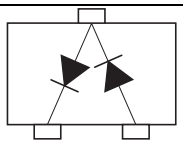
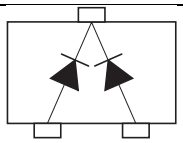
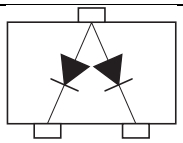
(3) 表示外形的英文字母标注方法
参照下表，用1个英文字母表示外形 （封装）。

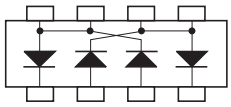
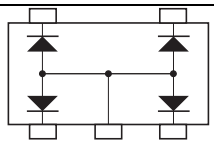
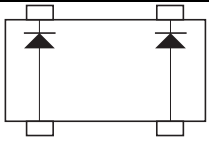
表示外形的英文字母	外形 （封装）
B	MOP、 CMPAK、 CMPAK-4,
C	UFP、 CMPAK的一部分
D	SFP
G	DO-35
K	LLD
L	EFP、 TEFP
M	MPAK、 MPAK-5

表示外形的英文字母	外形 （封装）
P	DO-41
R	SRP
S	MHD
T	温度补偿齐纳
U	URP
W	用于高速开关的MPAK

【注】 1. 除了需要与其他的封装特别区分的情况以外，可以省略英文字母 “G” (DO-35)。
（例：HZ6A1）
2. 虽然英文字母 “T”（温度补偿齐纳）并不属于外形部分，但是按以往的惯例，也包含在此表中。在需要表示封装时，可在 “T” 的后面添加相关的英文字母 （如 “TM”、“TK”）。

(4) 内部连接的表示方法
在1个封装内装入多个二极管时，原则上根据其连接状态来表示内部连接，具体如下所示：

内部连接	表示	内部连接电路
串联连接	S	
反向串联连接	SR	
阴极/公共	WK	
阳极/公共	WA	

内部连接	表示	内部连接电路
串联2个	WS	
4个器件共阳极	FA	
4个引脚并联	YP	

2. 高速开关二极管型号的命名方法

2.1 电流的表示方法

所谓电流，是指最大额定值的平均整流电流I_O或正向电流I_F，本规定的对象是I_O或I_F大于等于100mA的高速开关器件。原则上使用2位数表示型号中的电流值，如下所示。但是，对于大于等于1A的器件，当产品的I_O或I_F为1.2A等非整数时，舍去小数点以后的数字，并且当I_O或I_F的值表示到10mA位时，舍去10mA位上的数字。

[例] 平均整流电流I_O或I_F	表示电流
1A	1
20A	20
0.1A	01
1.2A	1

2.2 电压分类的表示方法

所谓电压，是指最大额定值V_{RRM}*，原则上是用十位和百位的 2 个数字表示该产品的V_{RRM}。另外，如果V_{RRM}的值表示到个位（如35V）时，舍去个位数。

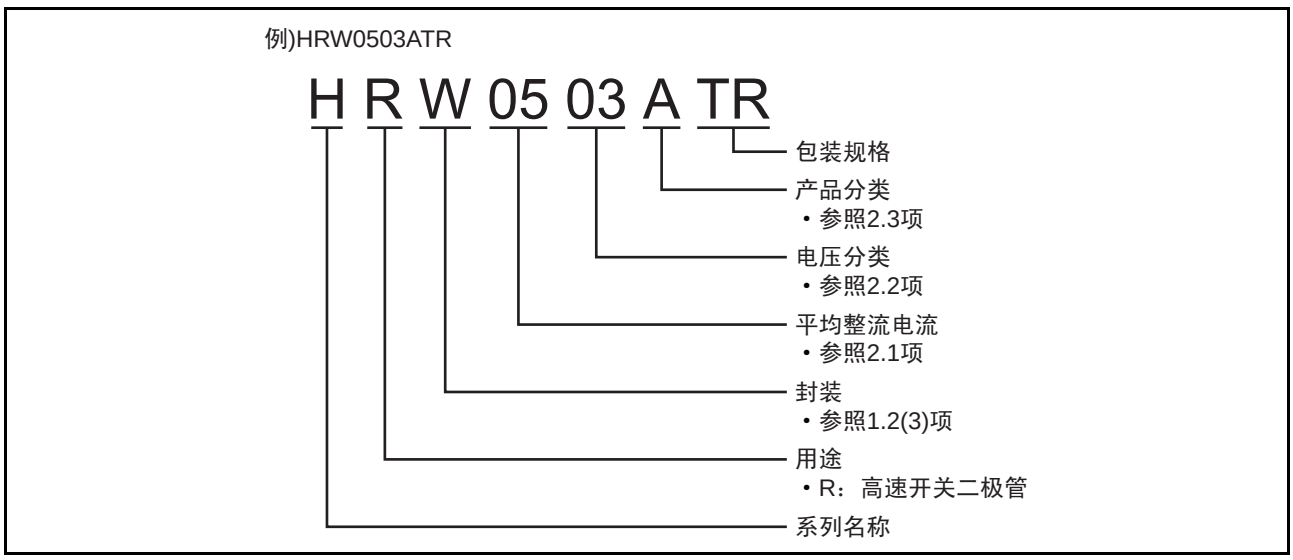
[例] 电压V_{RRM}	表示电压
10V	1
20V	02
35V	03
100V	10
800V	80

【注】 有时也用V_{RM}和V_R(peak)表示。

2.3 用英文字母表示的产品分类

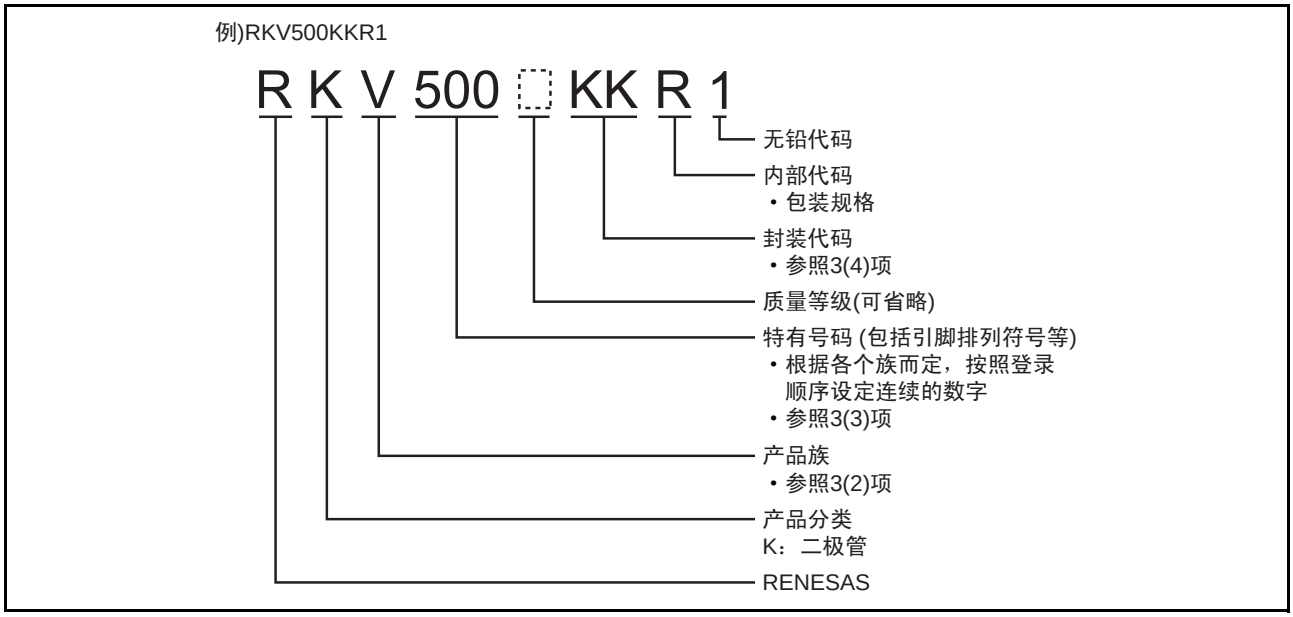
在相同电流 / 额定电压下，仅通过上述 2.1 和 2.2 项的分类方法并不能区分所有产品，如具有不同封装的产品。因此，通过在电压分类的后面标上英文字母，可进行产品的区分。此时，不使用英文字母「I」和「O」。

(1) 基本结构



3. 瑞萨型号的命名方法

(1) 基本结构



(2) 表示产品族的符号

符号	族
V	VC （调谐器/VCO）
P	PIN （衰减器/天线开关）
S	SW （开关/波段开关）
D	SS_SB
R	PR_SB （以整流电流值/耐压值为标准 *参照前页）
Z	ZN （以V_Z值为标准）

(3) 专用号码

号码 （连号）	族
100～149	开关
150～199	带开关
200～299	引脚 （天线开关）
300～399	引脚 （衰减器）

号码 （连号）	族
400～499	多种PIN系列封装产品
500～599	变容二极管 （调谐器）
600～699	变容二极管(VCO)
700～799	小信号肖特基二极管

(4) 表示外形的英文字母的标注方法

表示外形的英文字母	外形（封装）
KA	DO-35
KB	DO-41
KC	MHD
KD	LLD
KF	SRP
KG	URP
KH	TURP
KJ	UFP

表示外形的英文字母	外形（封装）
KK	SFP
KL	EFP
KM	TEFP
KN	MP8
KP	MP6
KR	MOP
KT	VSON-5
KS	MFP12

表示外形的英文字母	外形（封装）
KE	MAP系列
QA	MPAK
QC	MPAK5
QE	CMPAK
QF	CMPAK4
QK	MFPAK
WA～WF	晶片出货1～6
WT～WR	芯片出货1～6

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